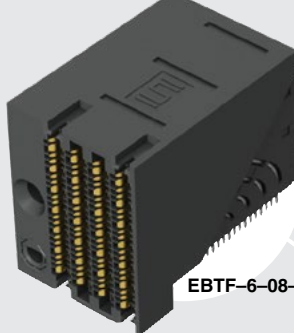
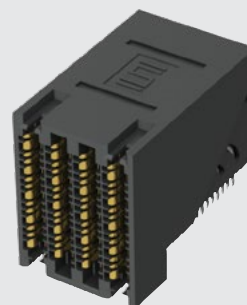


# ExaMAX<sup>®</sup>

(2.00 mm) .0787"



EBTF-6-08-2.0-S-RA-1-L-A



EBTF-4-08-2.0-S-RA-1

## ExaMAX<sup>®</sup> BACKPLANE SYSTEM

### SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?EBTF-RA](http://www.samtec.com?EBTF-RA)

**Insulator Material:**  
Liquid Crystal Polymer

**Contact Material:**  
Copper Alloy

**Plating:**

Sn or Au over  
50 μ" (1.27 μm) Ni

**Operating Temp Range:**  
-55 °C to +105 °C

**Current Rating:**  
4.2 A per pin  
(1 pin powered)

**Contact Wipe:**  
2.4 mm

**RoHS Compliant:**  
Yes

**Mates with:**  
EBTM, EBDM

2.00 mm  
column pitch

PAM 4

56

G b p s

Press-fit  
termination

Two reliable  
points of contact  
with 2.4 mm wipe

### RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

EBTF

NO. OF PAIRS  
PER COLUMN

COLUMNS

COLUMN  
PITCH

-4 = 4 Pairs

-6 = 6 Pairs

-06

-08

-10

-12  
(-6 only)-2.0  
= (2.0 mm)  
.0787"

### ALSO AVAILABLE (MOQ Required)

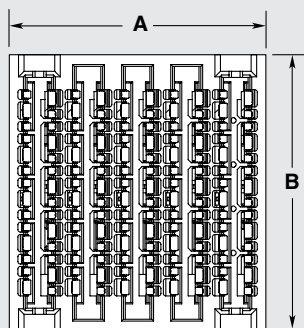
- Staging

### TOOLING

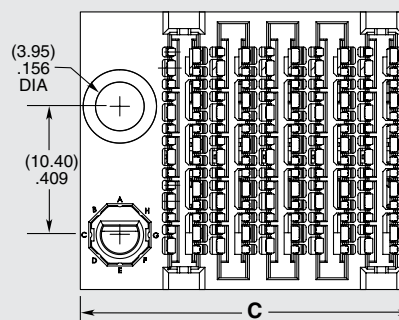
- For press-fit extraction and insertion tool options, visit [www.samtec.com/tooling](http://www.samtec.com/tooling)

NO. OF PAIRS PER COLUMN	B
-4	(22.50) .886
-6	(29.70) 1.169

COLUMNS	A	C
-06	(12.90) .508	(18.85) .742
-08	(16.90) .665	(22.85) .900
-10	(20.90) .823	(26.85) 1.057
-12	(24.90) .980	(30.85) 1.215



NO GUIDANCE SHOWN



WITH GUIDANCE SHOWN

**Notes:**  
Some lengths, styles and options are non-standard, non-returnable.

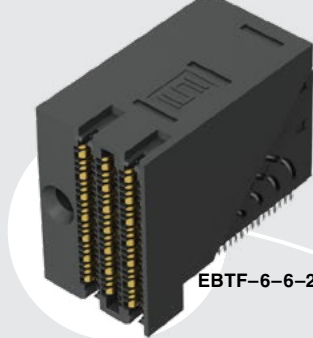
ExaMAX<sup>®</sup> is a registered trademark of AFCL.

Due to technical progress, all designs, specifications and components are subject to change without notice.

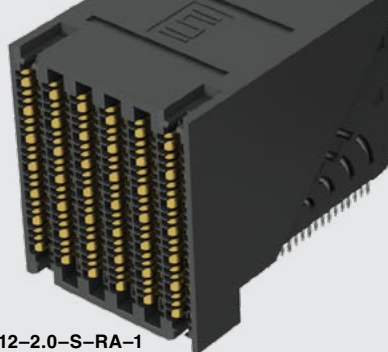
[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.

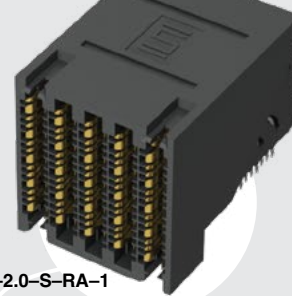
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.



EBTF-6-6-2.0-S-RA-1-L



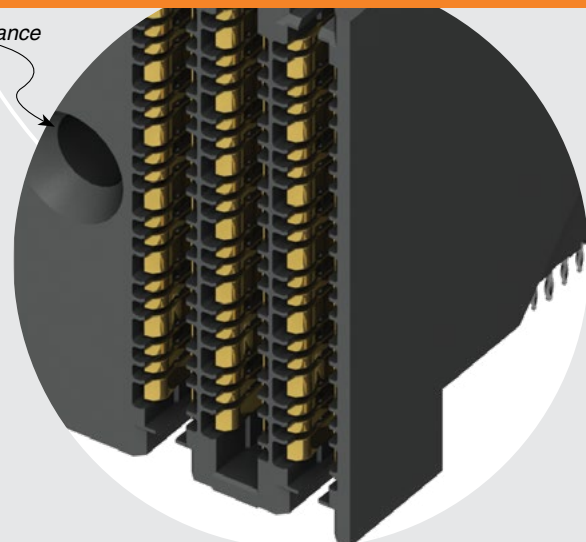
EBTF-6-12-2.0-S-RA-1



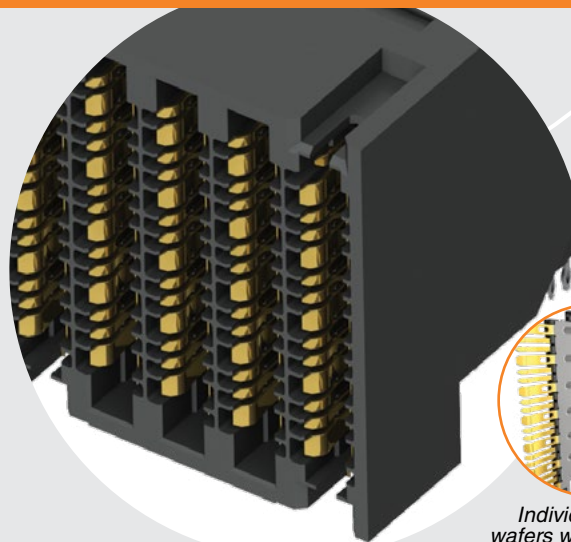
EBTF-4-10-2.0-S-RA-1

## EBTF-RA SERIES

Guidance



Press-fit termination



Individual signal wafers with one-piece ground plane

## PLATING

## RA

## 1

## GUIDANCE

## KEYING

### -S

= 30  $\mu$ m (0.76  $\mu$ m) Gold on contact area,  
Matte Tin on tail

(Leave Blank for no Guidance)

### -L

= Left Guidance

### -R

= Right Guidance

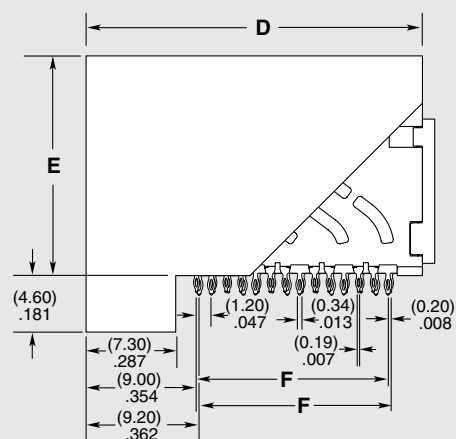
(Only available with -L or -R guidance)

(Leave Blank for no keying)

### -A thru -H

= Position of flat on Key  
(See table for Key)

GUIDANCE	KEYING							
	-A	-B	-C	-D	-E	-F	-G	-H
-R /-L								



EBTF-4-10-2.0-S-RA-1-L-A SHOWN

## APPLICATION



NO. OF PAIRS PER COLUMN	D	E	F
-4	(28.40) 1.118	(17.90) .705	(15.60) .614
-6	(35.60) 1.402	(25.10) .988	(22.80) .898

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

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